



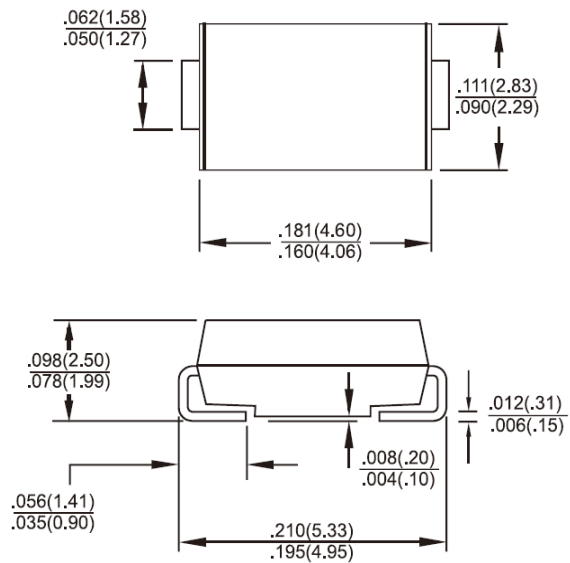
### Features

- ✧ Glass passivated junction chip
- ✧ For surface mounted application
- ✧ Low profile package
- ✧ Built-in strain relief
- ✧ Ideal for automated placement
- ✧ Easy pick and place
- ✧ Super fast recovery time for high efficiency
- ✧ Qualified as per AEC-Q101
- ✧ High temperature soldering:  
260 °C /10 seconds at terminals
- ✧ Plastic material used carries Underwriters  
Laboratory Classification 94V-0
- ✧ Green compound with suffix "G" on packing  
code & prefix "G" on datecode

### Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminals: Pure tin plated, lead free
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape per EIA STD RS-481
- ✧ Weight: 0.064 grams

## ESH1B - ESH1D 1.0AMP Surface Mount Super Fast Rectifiers SMA/DO-214AC



### Dimensions in inches and (millimeters)

#### Marking Diagram



- ESH1X = Specific Device Code
- G = Green Compound
- Y = Year
- M = Work Month

### Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	ESH1B	ESH1C	ESH1D	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	150	200	V
Maximum RMS Voltage	$V_{RMS}$	70	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	100	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0			A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load	$I_{FSM}$	30			A
Maximum Instantaneous Forward Voltage (Note 1) @ 1.0A	$V_F$	0.95			V
Maximum Reverse Current @ Rated VR $T_A=25\text{ }^\circ\text{C}$ $T_A=125\text{ }^\circ\text{C}$	$I_R$	1 25			$\mu\text{A}$
Maximum Reverse Recovery Time (Note 2)	$T_{rr}$	15			nS
Typical Junction Capacitance (Note 3)	$C_j$	16			pF
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	85 35			$^\circ\text{C/W}$
Operating Temperature Range	$T_J$	- 55 to + 175			$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	- 55 to + 175			$^\circ\text{C}$

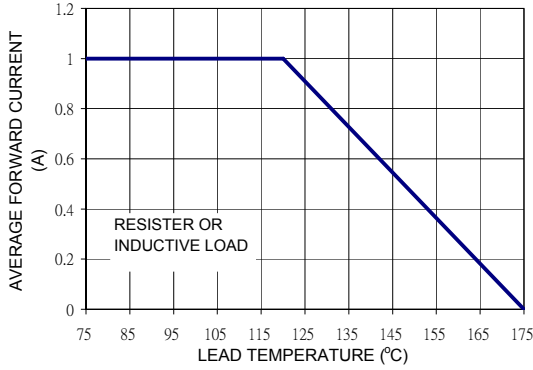
Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

Note 2: Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

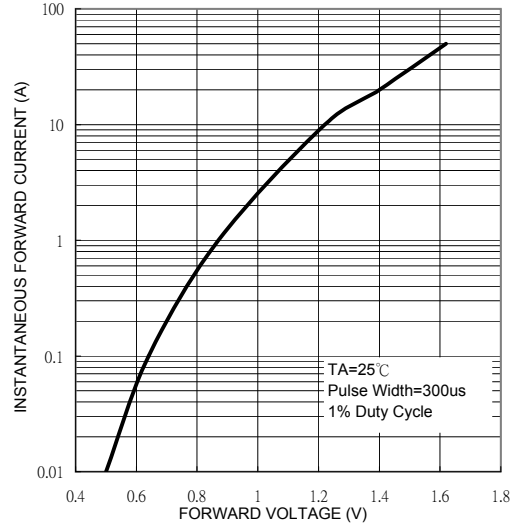
Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

**RATINGS AND CHARACTERISTIC CURVES (ESH1B THRU ESH1D)**

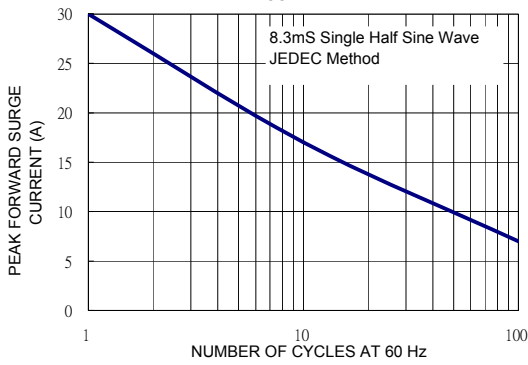
**FIG.1 FORWARD CURRENT DERATING CURVE**



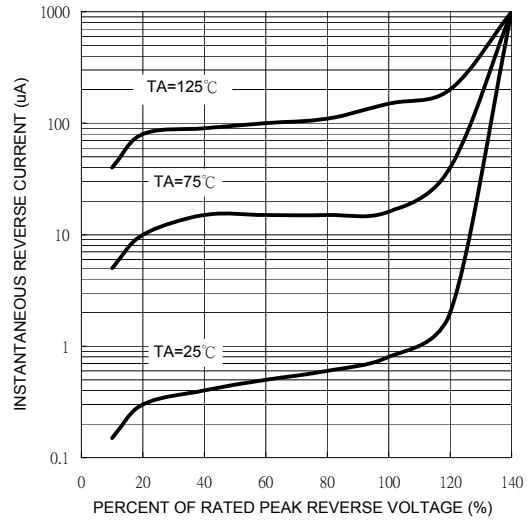
**FIG. 3 TYPICAL FORWARD CHARACTERISTICS**



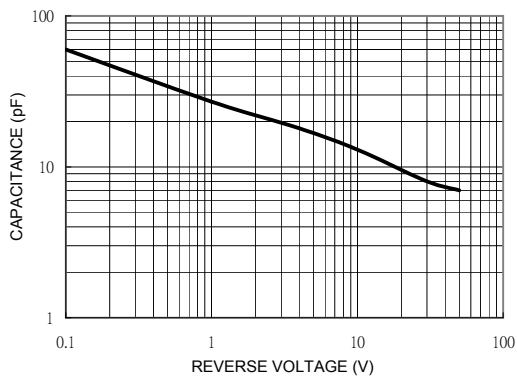
**FIG. 2 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG. 4 TYPICAL REVERSE CHARACTERISTICS**



**FIG. 5 TYPICAL JUNCTION CAPACITANCE**



**FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM**

